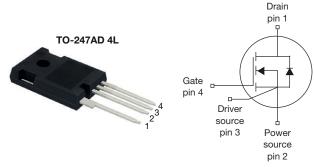


# MaxSiC® 1200 V N-Channel SiC MOSFET



Marking Code: Q120A080SL

PRODUCT SUMMARY				
V <sub>DS</sub> (V) at T <sub>J</sub> max.	1200			
R <sub>DS(on)</sub> typ. (mΩ) at 25 °C	V <sub>GS</sub> = 18 V	80		
Q <sub>g</sub> typ. (nC)	45			
I <sub>D</sub> (A)	31			
C <sub>oss</sub> typ. (pF)	56			
P <sub>D</sub> (W)	174			
Configuration	Single			

#### **FEATURES**

- · Fast switching speed
- Short circuit withstand time 3 µs
- AEC-Q101 qualified
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912



### **APPLICATIONS**

- · Automotive on board charger
- Automotive DC/DC converter for EV / HEV
- Auxiliary drives
- · EV charging

ORDERING INFORMATION	
Package	TO-247AD 4L
Lead (Pb)-free and halogen-free	MXPQ120A080SL-GE3
Lead (Pb)-free and halogen-free	MXPQ120A080SL-GE3

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		$V_{DS}$	1200		
Gate-source voltage		$V_{GS}$	-10 / +22	V	
Recommended operation voltage of gate-source		$V_{GSOP}$	-5 to -3 / +18		
Continuous drain current	T <sub>C</sub> = 25 °C	I <sub>D</sub>	31	^	
Pulsed drain current a	<u>.</u>	I <sub>DM</sub>	62	A	
Short-circuit withstand time <sup>b</sup>		T <sub>SC</sub>	3	μs	
Maximum power dissipation	T <sub>C</sub> = 25 °C	P <sub>D</sub>	174	W	
Operating junction and storage temperature range	<u>.</u>	T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C	
Soldering recommendations (peak temperature)	For 10 s		260	°C	
Single pulse avalanche energy <sup>c</sup>	<u>.</u>	E <sub>AS</sub>	113	mJ	

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b.  $V_{GS}$  = 18 V,  $V_{DS}$  = 800 V,  $R_{g(ext)}$  = 20  $\Omega$ , verified by the design / characterization
- c.  $T_J = 25$  °C,  $V_{DD} = 120$  V, L = 1 mH,  $V_{GS} = 18$  V,  $I_{AS} = 15$  A, verified by the design / characterization



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THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	$R_{thJA}$	-	40	°C/W	
Maximum junction-to-case (drain)	$R_{thJC}$	-	0.86	C/VV	

<b>SPECIFICATIONS</b> ( $T_J = 25  ^{\circ}\text{C}$ ,		-			_	I	
PARAMETER	SYMBOL	TEST CONDIT	MIN.	TYP.	MAX.	UNIT	
Static					1	ı	1
Drain-source breakdown voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}$		1200	-	-	V
Gate-source threshold voltage (N)	V <sub>GS(th)</sub>		$V_{DS} = V_{GS}$ , $I_D = 2.8 \text{ mA}$		2.9	-	V
acto socioo inconoid voitage (14)	- GS(III)		$V_{DS} = V_{GS}$ , $I_{D} = 2.8$ mA, $T_{J} = 175$ °C		2.0	-	V
Gate-source leakage	I <sub>GSS</sub>	$V_{GS} = 22 \text{ V}, V_{DS} = 0 \text{ V}$		-	-	100	nA
<u> </u>	-033	$V_{GS} = -10 \text{ V}, V_{D}$		-	-	-100	
Zero gate voltage drain current	I <sub>DSS</sub>	$V_{DS} = 1200 \text{ V}, V_{C}$		-	-	10	μΑ
			V <sub>GS</sub> = 15 V, I <sub>D</sub> = 14 A		97	121	mΩ
Drain-source on-state resistance	R <sub>DS(on)</sub>		V <sub>GS</sub> = 18 V, I <sub>D</sub> = 14 A		80	100	
		$V_{GS} = 18 \text{ V}, I_D = 14 \text{ A}$		-	144	-	
Transconductance	gfs	$V_{DS} = 10 \text{ V}, I_D = 10 \text{ V}$	= 14 A	-	5.5	-	S
Dynamic							
Input capacitance	C <sub>iss</sub>			-	1356	-	
Output capacitance	C <sub>oss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 800 V, f = 100 KHz		-	56	-	pF
Reverse transfer capacitance	$C_{rss}$			-	2	-	
Total gate charge	$Q_g$	$V_{GS} = -5 \text{ V} \sim 18 \text{ V}, I_D = 14 \text{ A}, V_{DS} = 800 \text{ V}$		-	45	-	nC
Gate-source charge	Q <sub>gs</sub>			-	14	-	
Gate-drain charge	Q <sub>gd</sub>			-	12	-	
Gate Resistance	Rg	V <sub>DS</sub> = 0 V, f = 1 MHz		-	4	-	Ω
Switching Characteristics							
Turn on deleviting	1		T <sub>J</sub> = 25 °C	-	14	-	
Turn-on delay time	t <sub>d(on)</sub>	$T_{\rm J} = 175$ °C	T <sub>J</sub> = 175 °C	-	13	-	
Die a time a	1		T <sub>J</sub> = 25 °C	-	12	-	ns
Rise time	t <sub>r</sub>		T <sub>J</sub> = 175 °C	-	12	-	
Town off delections			T <sub>J</sub> = 25 °C	-	17	-	
Turn-off delay time	t <sub>d(off)</sub>	$V_{GS} = -5 \text{ V} \sim 18 \text{ V},$	T <sub>J</sub> = 175 °C	-	18	-	
Fall times		$I_D = 14 \text{ A}, V_{DS} = 800 \text{ V},$ $R_{q(ext)} = 4.4 \Omega$	T <sub>J</sub> = 25 °C	-	10	-	
Fall time	t <sub>f</sub>	· · · · · · · · · · · · · · · · · · ·	T <sub>J</sub> = 175 °C	-	10	-	
T	_		T <sub>J</sub> = 25 °C	-	132	-	μJ
Turn-on switching energy	E <sub>on</sub>		T <sub>J</sub> = 175 °C	-	119	-	
	_		T <sub>J</sub> = 25 °C	-	42	-	
Turn-off switching energy	E <sub>off</sub>		T <sub>J</sub> = 175 °C	-	42	-	
<b>Body Diode Ratings and Characteristic</b>	;						
Forward diode voltage	V <sub>SD</sub>	V <sub>GS</sub> = -5 V, I <sub>SD</sub> = 7 A, T <sub>J</sub> = 25 °C		-	4.7	_	V
Continuous diode forward current	I <sub>SD</sub>	V <sub>GS</sub> = -5 V, T <sub>J</sub> = 25 °C		-	-	24	
Pulsed diode forward current	I <sub>SDM</sub>			-	-	62	Α
Reverse recovery time	t <sub>rr</sub>	V <sub>GS</sub> = -5 V, I <sub>SD</sub> = 14 A, V <sub>R</sub> = 800 V, di/dt = 1000 A/μs		-	16	-	ns
Reverse recovery charge	Q <sub>rr</sub>			-	47	-	nC
Reverse recovery current	I <sub>RRM</sub>			_	5	_	Α

### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

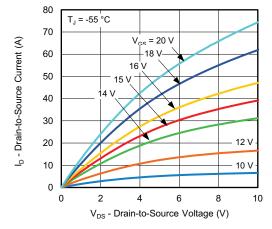


Fig. 1 Typical Output Characteristics

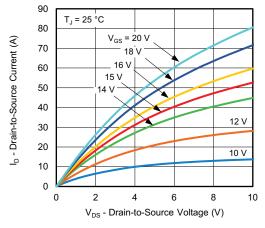


Fig. 2 Typical Output Characteristics

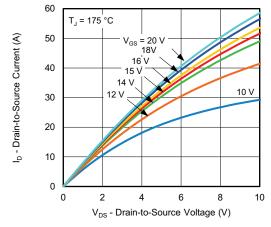


Fig. 3 Typical Output Characteristics

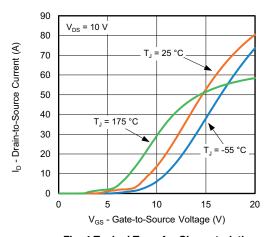


Fig. 4 Typical Transfer Characteristics

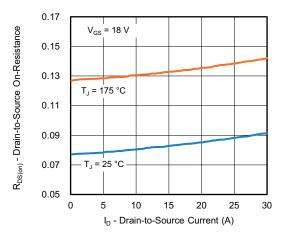


Fig. 5 Normalized On-Resistance vs. Drain Current

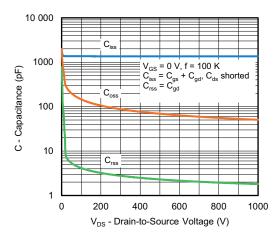


Fig. 6 Typical Capacitance vs. Drain-to-Source Voltage



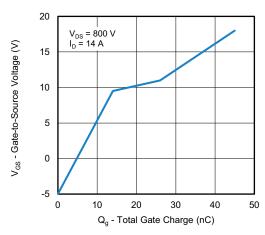


Fig. 7 Typical Gate Charge vs. Gate-to-Source Voltage

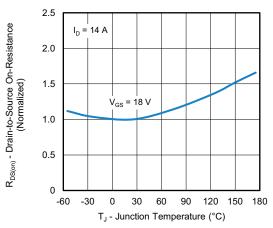


Fig. 8 Normalized On-Resistance vs. Temperature

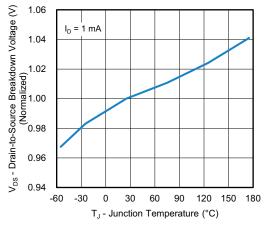


Fig. 9 Drain-to-Source Voltage vs. Temperature

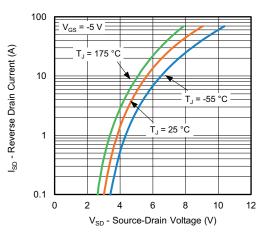


Fig. 10 Typical Source-Drain Diode Forward Voltage

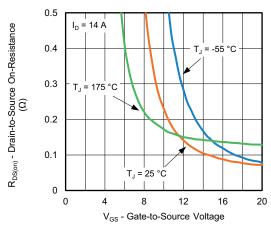


Fig. 11On-Resistance vs. Gate-to-Source Voltage

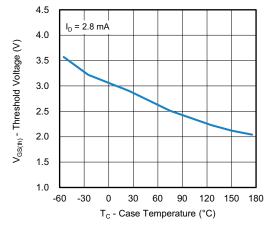


Fig. 12 Threshold Voltage vs. Case Temperature

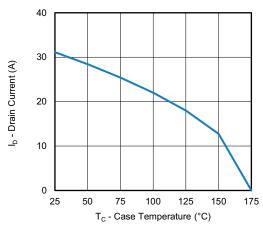


Fig. 13 Drain Current vs. Case Temperature

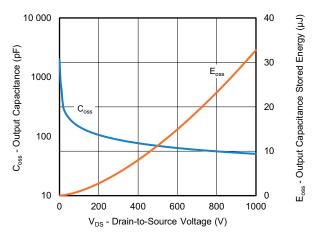


Fig. 14 Output Capacitance and its Stored Energy vs. Drain-to-Source Voltage

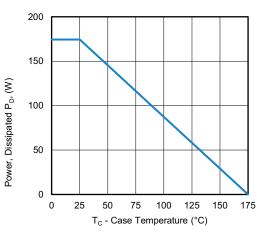


Fig. 15 Power, Dissipated P<sub>D</sub> vs. Case Temperature

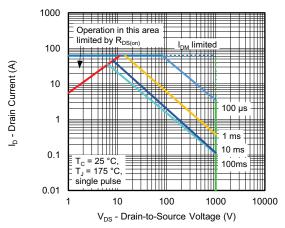


Fig. 16 Safe Operating Area

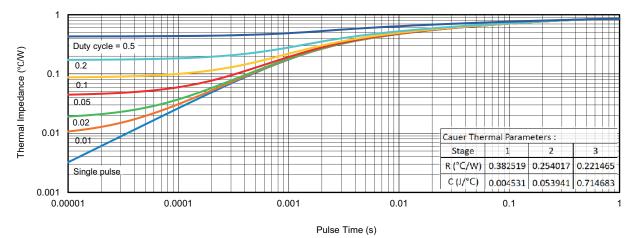


Fig. 17 Transient Thermal Impedance



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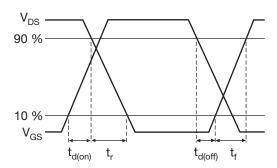
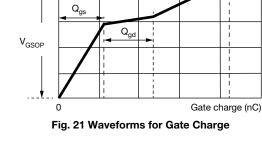


Fig. 18 Waveforms of Switching Time



 $Q_g$ 

 $V_{G}(V)$ 

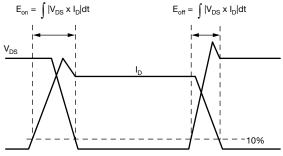


Fig. 19 Waveforms for Switching Energy

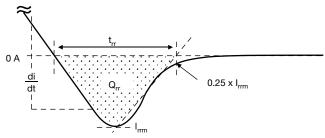


Fig. 22 Waveforms for Reverse Recovery

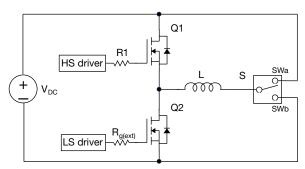


Fig. 20 Switching and Reverse Diode Characteristics Measurement Circuit

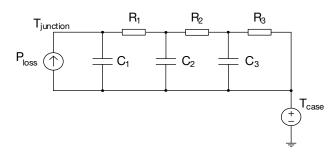


Fig. 23 Thermal Equivalent Circuit

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